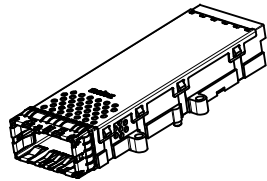
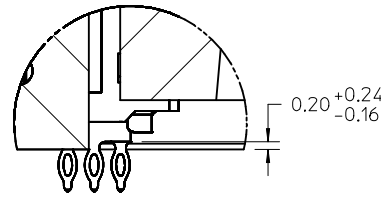
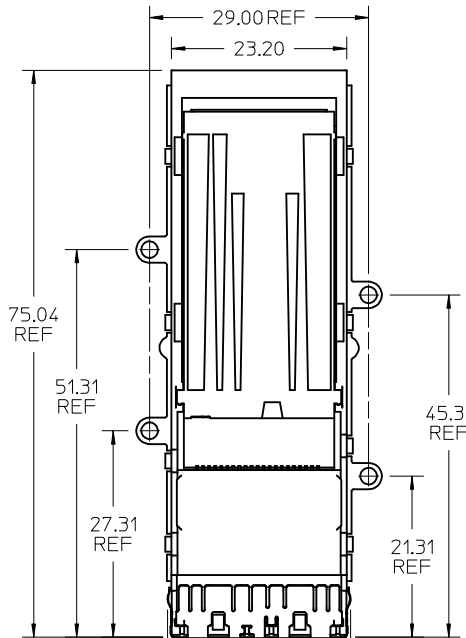


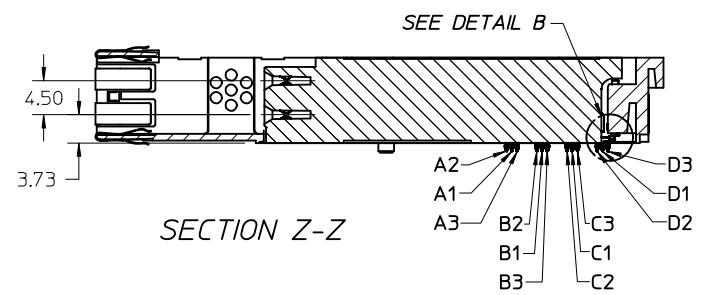
1705020001



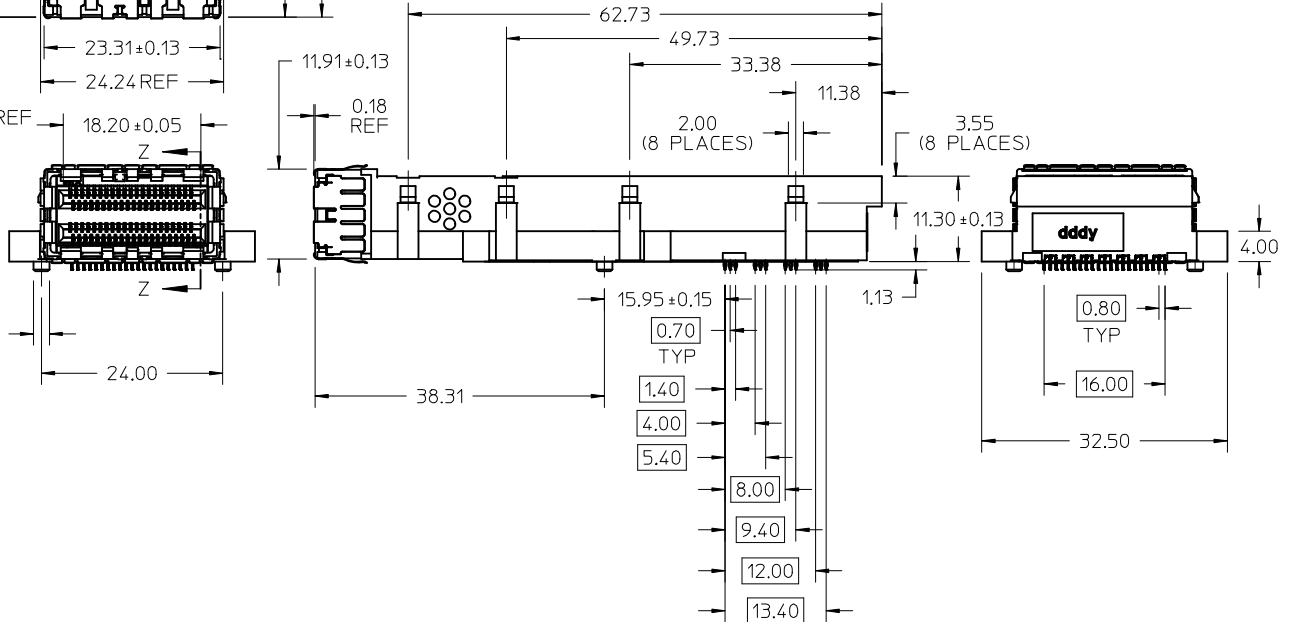
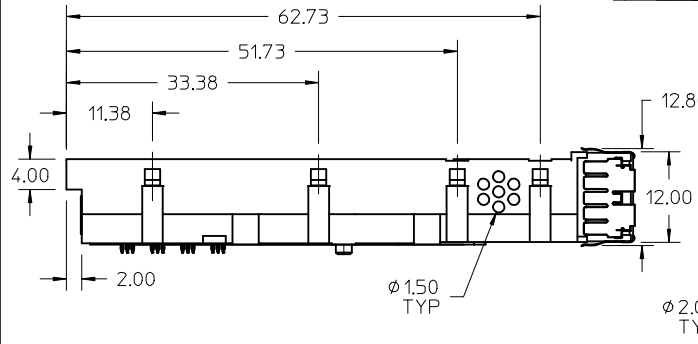
1705021001



DETAIL B
SCALE 10:1



SECTION Z-Z

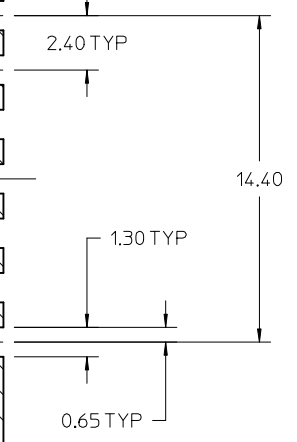
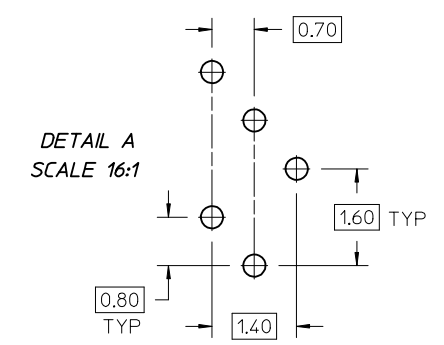
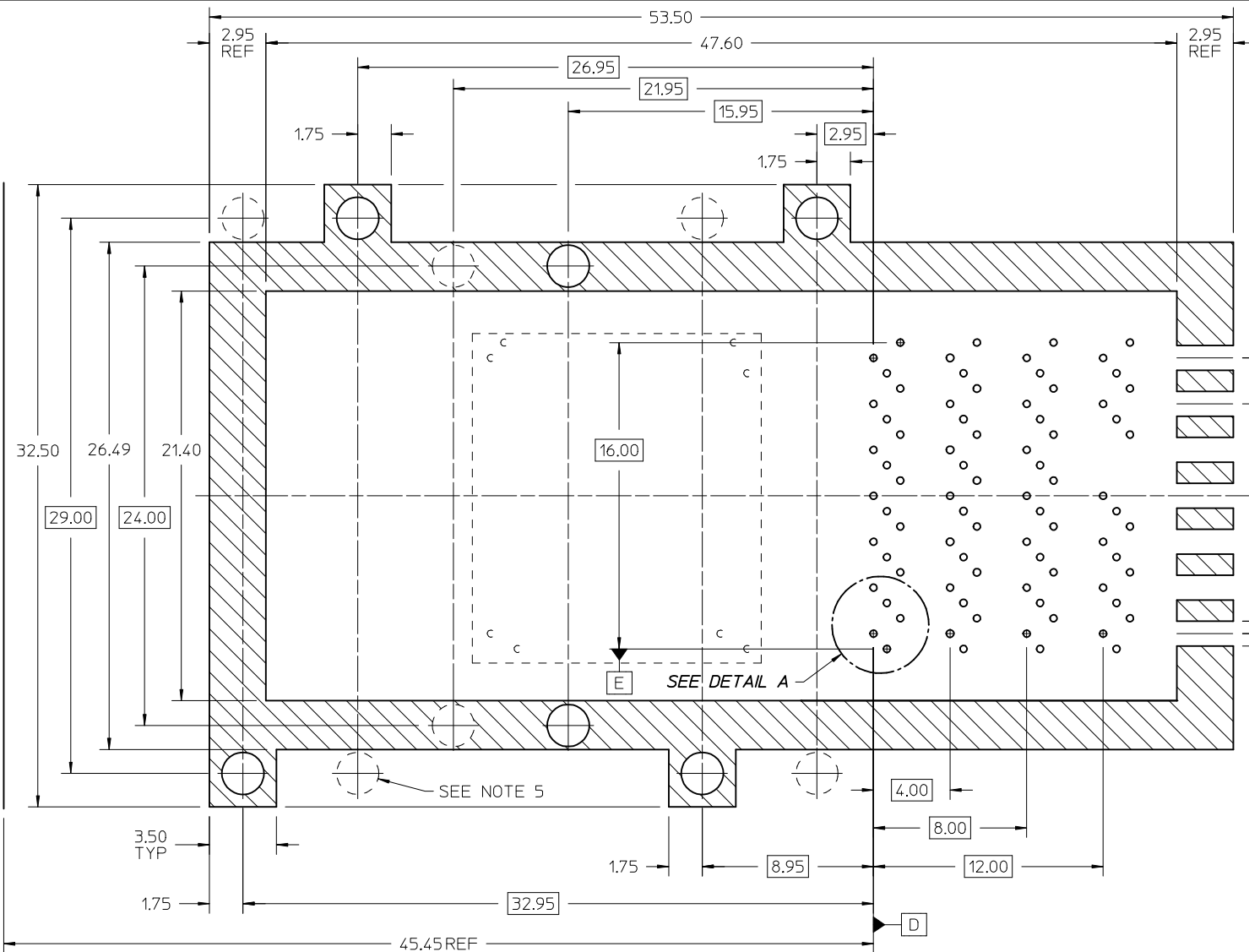


- NOTES:
- MATERIALS:**
 CONNECTOR HOUSING: HIGH TEMPERATURE THERMOPLASTIC GLASS-FILLED, UL 94V-0
 EMI HOUSING: NICKEL PLATED DIE CAST ALLOY
 COVER: STAINLESS STEEL ALLOY
 EMI CLIPS: NICKEL PLATED PHOS BRONZE
 TERMINALS: COPPER ALLOY
 - PLATING:**
 CONTACT AREA: 0.76µm MIN. GOLD OVER 2.54µm MIN. NICKEL
 TAIL AREA: 0.76µm - 1.52µm TIN OVER 1.27µm MIN NICKEL
 - THIS CONNECTOR IS DESIGNED TO MATE WITH MOLEX CABLE SERIES INDICATED IN THE MOLEX PRODUCT SPEC. PS-170502-0001.
 - REFER TO ROUTING GUIDE AS-170501-0002 FOR PCB TRACE INFORMATION.
 - PACKAGING SPECIFICATION: TRAY PACK PER PK-170502-0001.
 - REFER TO AS-170501-0001 FOR THE APPLICATION SPECIFICATION.
 - MOUNTING HARDWARE REQUIRED: M2x0.4 CAP SCREWS (6)
 MOUNTING SCREW LENGTH: BOARD THICKNESS + 4mm MAX
 - THERMAL SOLUTION MUST PROVIDE MODULE GUIDANCE OR MODULE MAY STUB ON CONNECTOR DURING MATING.
 SAME FUNCTION AS COVER OR HEATSINK.

MATERIAL	DESCRIPTION
1705020001	NO COVER
1705021001	WITH COVER

ADD TOL., CUT-OUT EC NO: UCP2013-2408 DRAWING PRATT 2012/12/12 CHKD: MBANAKIS 2012/12/12 APPR: MBANAKIS 2012/12/18	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	mm INCH ± --- ± --- ± 0.25 ± --- ± --- ± ---	DRAWN BY JLONG	DATE 2010/06/03	TITLE IPASS+ CXP EF EXTENDED 84 CIRCUIT, 0.8MM I/O		MOLEX INCORPORATED	
REV C2	DESCRIPTION CUT-OUT	ANGULAR ±1/2°		APPROVED BY MBANAKIS		DATE 2012/12/18	DOCUMENT NO. SD-170502-0001		SHEET NO. 1 OF 5
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

EDGE OF BOARD

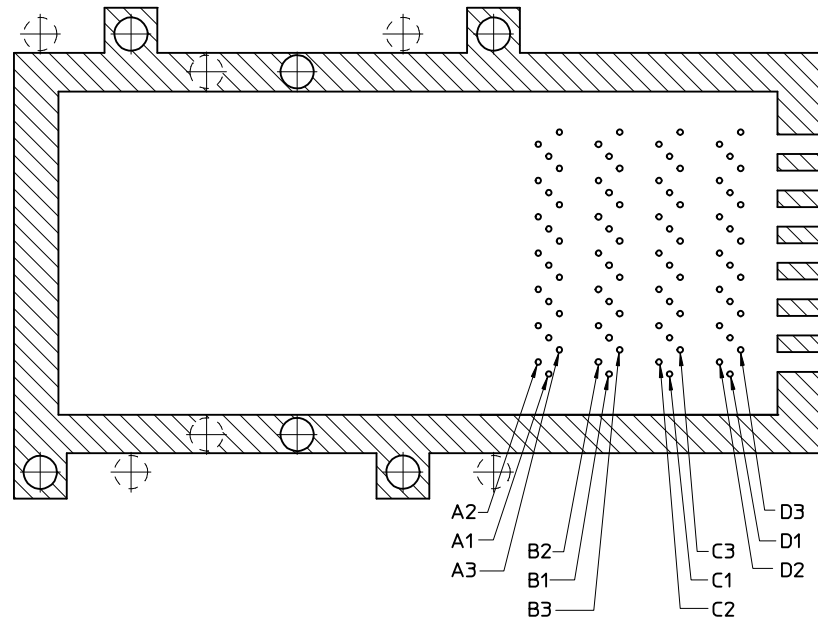
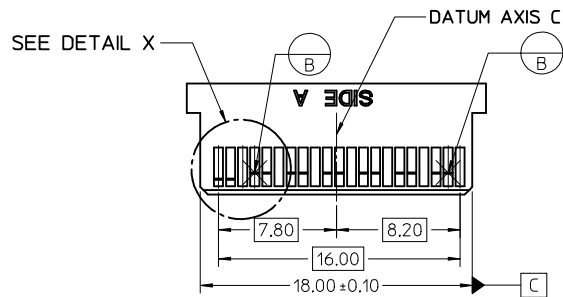
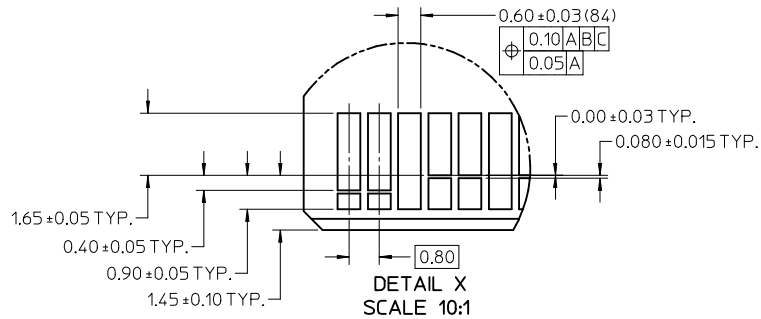
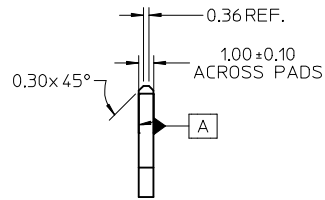
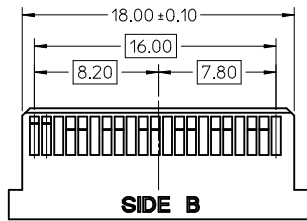


RECOMMENDED PCB LAYOUT
COMPONENT SIDE SHOWN

PCB THICKNESS: 1.44mm MIN.

- NOTES:
- CROSS-HATCHED AREA TO BE CONDUCTIVE ON THE PCB.
 - CROSS-HATCHED AREA MUST BE INCORPORATED IN THE FLAT ROCK PRESS-FIT TOOLING.
 - REFER TO THE PLATING DETAIL OF THE COMPLIANT PIN HOLES IN THE APPLICATION SPEC AS-170465-0002 FOR THE DRILL SIZE AND ANNULAR RING FOR THE 0.37 ϕ FINISHED HOLE.
 - MINIMUM RECOMMENDED SPACING: 29.00
 - FEATURES IN PHANTOM LINES ARE RELATED FOR USE WITH CONNECTOR ASSEMBLY SERIES 170501 FOR GANGED SIDE BY SIDE AND BELLY TO BELLY APPLICATIONS.
 - NO SIGNAL ROUTING ON TOP LAYER.

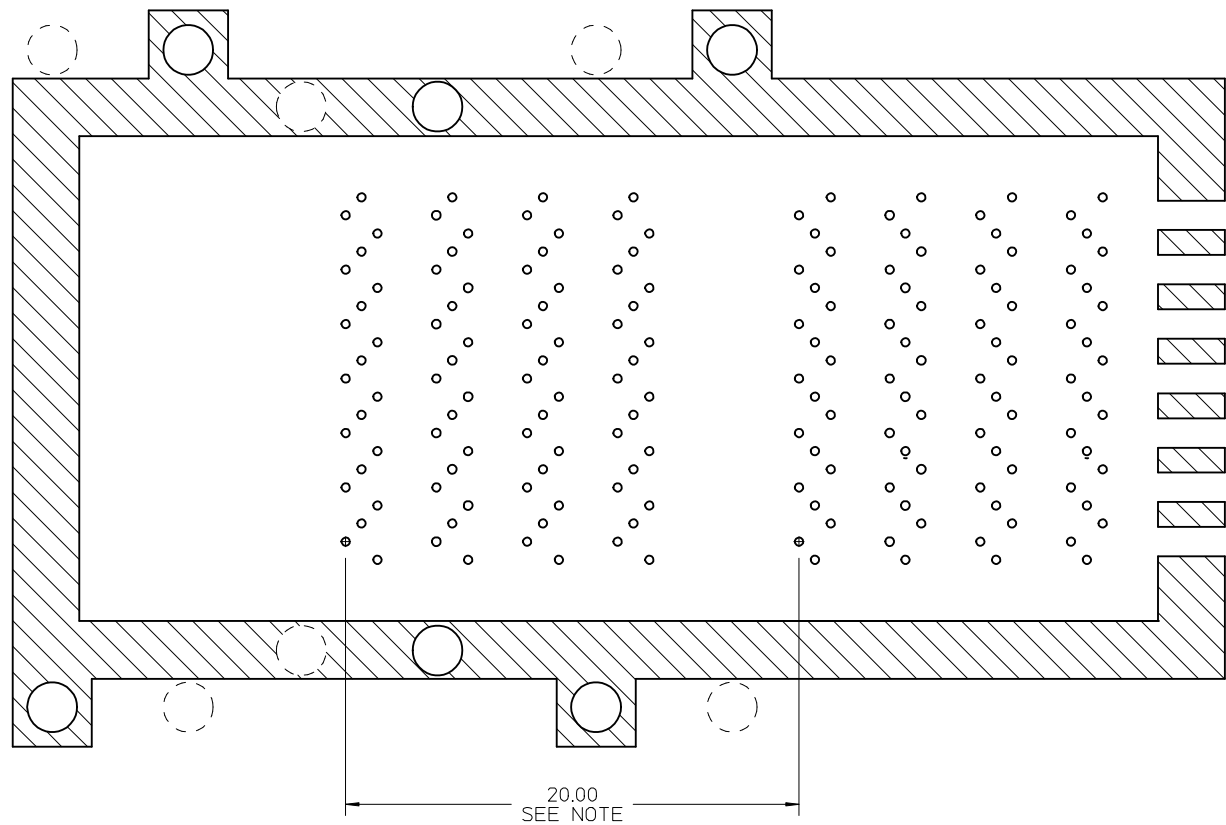
SE SHEET 1 EC NO: UCP2013-2408 DRAWING PRATT 2012/12/12 CHKD: MBANAKIS 2012/12/17 APPR: MBANAKIS 2012/12/18	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 6:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY JLONG	DATE 2010/06/03	TITLE IPASS+ CXP EF EXTENDED 84 CIRCUIT, 0.8MM I/O	MOLEX INCORPORATED		
C2	REV	4 PLACES ± --- ± ---		CHECKED BY JLONG		DATE 2010/06/03		APPROVED BY MBANAKIS	
		3 PLACES ± --- ± ---		DATE 2012/12/18		DOCUMENT NO. SD-170502-0001		SHEET NO. 2 OF 5	
		2 PLACES ± 0.25 ± ---		MATERIAL NO. 1705020001		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		1 PLACE ± --- ± ---		ANGULAR ± 1/2°					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							



NOTES:

- 0.03 MINIMUM KEEP OUT FOR SOLDER MASK AROUND ALL PADS
- DATUM B TARGETS ARE DEFINED BY THE RESPECTIVE PAD CENTER LINES AND THE LEADING EDGE OF THE TARGET PADS

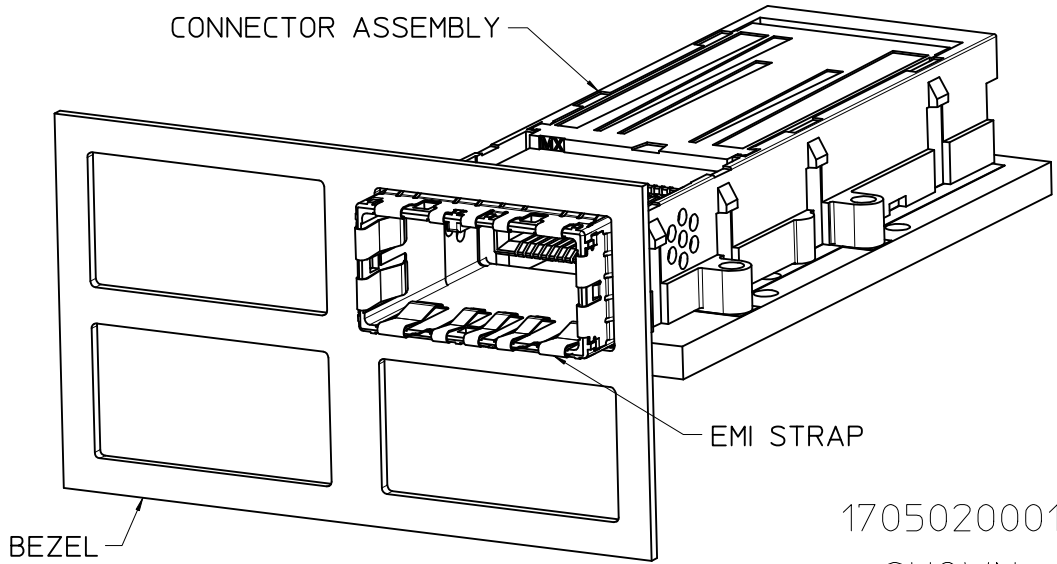
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		mm	INCH	DRAWN BY JLONG	DATE 2010/06/03	TITLE IPASS+ CXP EF EXTENDED 84 CIRCUIT, 0.8MM I/O		
		4 PLACES ± ---	± ---	CHECKED BY JLONG	DATE 2010/06/03	MOLEX INCORPORATED DOCUMENT NO. SD-170502-0001		
		3 PLACES ± ---	± ---	APPROVED BY MBANAKIS	DATE 2012/12/18			
2 PLACES ± 0.25	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
1 PLACE ± ---	± ---							



NOTE:
1. WHEN USED WITH CONNECTOR SERIES 170501
VIA PATTERN WILL APPEAR AS SHOWN.

SEE SHEET 1 EC NO: UCP2013-2408 DRAWING PRATT 2012/12/12 CHKD: MBANAKIS 2012/12/12 APPR: MBANAKIS 2012/12/18	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 6:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	▽=0	mm	INCH	DRAWN BY JLONG	DATE 2010/06/03	TITLE IPASS+ CXP EF EXTENDED 84 CIRCUIT, 0.8MM I/O			
	▽=0	4 PLACES ± ---	± ---	CHECKED BY JLONG	DATE 2010/06/03				
	▽=0	3 PLACES ± ---	± ---	APPROVED BY MBANAKIS		DATE 2012/12/18	MOLEX INCORPORATED DOCUMENT NO. SD-170502-0001		SHEET NO. 4 OF 5
C2	DESCRIPTION	2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

CONNECTOR ASSEMBLY



BEZEL

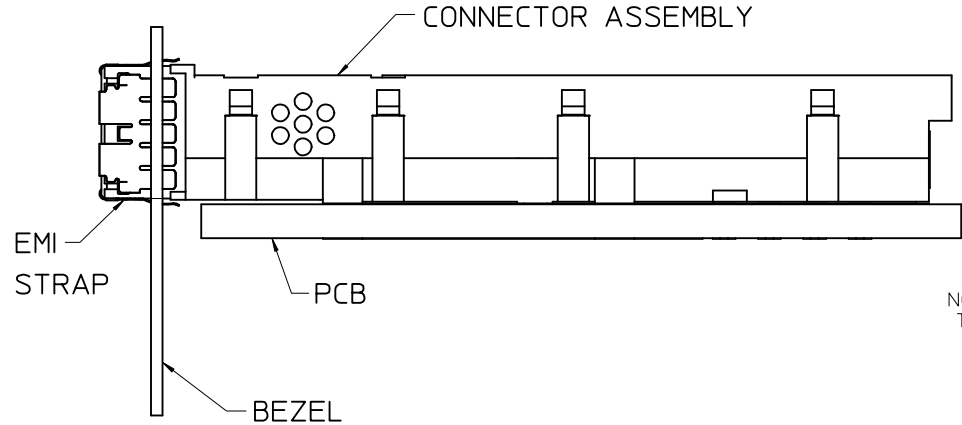
EMI STRAP

1705020001
SHOWN

DIM "A"	DIM "B"	DIM "C"	MINIMUM PCB
3.10	3.32	15.67	10% NOM THK
1.60	1.82	14.17	1.44
2.80	3.02	15.37	10% NOM THK

NOTE: WITH 1.44 MINIMUM PCB THICKNESS, WILL NOT SUPPORT PLUGS WITH GREATER THAN 28 AWG CABLE.

CONNECTOR ASSEMBLY



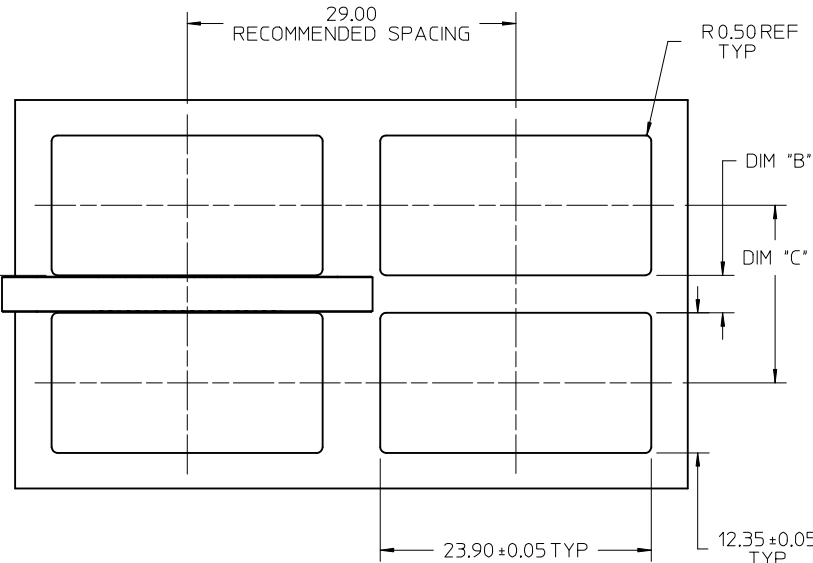
EMI STRAP

PCB

BEZEL

0.12 ABOVE NOMINAL PCB

DIM "A" NOMINAL PCB THICKNESS



SEE SHEET 1 EC NO: UCP2013-2408 DRAWING: GPRATT 2012/12/12 CHKD: MBANAKIS 2012/12/12 APPR: MBANAKIS 2012/12/18	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1/2°	DIMENSION STYLE MM ONLY DRAWN BY DATE JLONG 2010/06/03 CHECKED BY DATE JLONG 2010/06/03 APPROVED BY DATE MBANAKIS 2012/12/18	SCALE 3:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE IPASS+ CXP EF EXTENDED 84 CIRCUIT, 0.8MM I/O	MOLEX INCORPORATED
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. 1705020001	DOCUMENT NO. SD-170502-0001	SHEET NO. 5 OF 5		
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
	C2	REV	SIZE C	SIZE		